Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP Pro 3300 Series Small Form Factor (SFF) PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Motherboard, power supply, graphics card</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries located on motherboard</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>The quantity may vary</td>
<td>6</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>System fan, processor fan and power supply fan</td>
<td>3</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel from the unit
2. Remove front bezel from the unit.
3. Remove ODD from the unit.
4. Remove HDD from the unit.
5. Remove all the cables from PCA
6. Take off memory from the PCA
7. Take off graphic card
8. Take off FIO from the unit
9. Take off CPU Cooler
10. Take off CMOS battery
11. Take off system fan
12. Take off PCA from the Unit
13. Take off PSU from the Unit
14. Open the PSU
15. Remove capacitors greater than 2.5cm in height or diameter (quantity may vary)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove access panel from the unit

Release the screw and slide the access panel and remove it.
2. Take off the front bezel
Release 3 bezel latches from chassis by pulling outwards the bezel latches

3. Remove ODD from the unit.
Rotate the ODD Cage to vertically location and then release ODD screw align with the cage screw holes

4. Remove HDD from the unit.

PSG instructions for this template are available at EL-MF877-01
5. Remove all the cables from PCA.

6. Take off Memory from the unit.
Release memory socket levers by pulling outward.

7. Take off graphic card
   a. Release screw in location as shown.
b. Release graphic card from the slot.

8. Take off FIO from the unit
9. Take off CPU Cooler.

10. Take off CMOS battery
    Pull the battery holder as shown in the photo, and then the battery will off the PCA.
<table>
<thead>
<tr>
<th>Step</th>
<th>Description</th>
</tr>
</thead>
</table>
| 11.    | Take off system fan  
|        | Rotate screw driver to loose screw and then take off the system fan. |
| 12.    | Take off PCA from the Unit  
|        | Use screw driver to loose screws and then take the PCA off the Unit |
13. Take off PSU from the Unit
Use screwdriver to loose screws and then take the PSU off the Unit

14. Open the PSU